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FORM COVER SHEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 062807-0424

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Osamu KOMURO, Osamu NASU

Additional name(s) of conveying party(ies)attached? ☐ Yes ☐ No

2. Name and address of receiving party(ies)

Name: **HITACHI HIGH-TECHNOLOGIES CORPORATION**

Internal Address:

Address: **24-14, Nishishinbashi 1-chome, Minato-ku,**
Tokyo, JAPAN

11/723579

Additional name(s) & address(es) attached? ☐ Yes ☐ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **February 22, 2007**

☒ **Assignment**
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Joint Research Agreement
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☐ Executive Order 9424, Confrmatory License
☐ Other

4. Application or patent number(s):

☒ This document is being filed together with a new applicatic

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP
Internal Address:
Street Address: 600 13th Street, N.W.
City: Washington State: D. C. Zip: 20005-3096
Phone Number: 202.756.8000
Fax Number: 202.756.8087
Email Address:

04/04/2007 DBYRNE 00000144 500417 11723579
01 FC:8021 40.00 DA

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $40.00

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Keith E. George, 34,111 Keith E. George March 21, 2007

Name and Registration No. of Person Signing Signature Date

Total number of pages including cover sheet, attachments and documents: 2

OMB No. 0651-0027 (exp. 6/30/2008)

ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishishinbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Osamu Komuro Osamu KOMURO	2/22/2007
2)	Osamu Nasu Osamu NASU	2/22/2007
3)		
4)		
5)		
6)		
7)		
8)		
9)		
10)		